HEAT DISSIPATION INTERFACE FOR SEMICONDUCTOR CHIP STRUCTURES

ABSTRACT

The present invention is directed to a modular heat dissipating device that consists of a plurality of sheet and beam members which are connected together by heat pipes. The sheet or support fin member is constructed by folding a piece of heat conducting material which is then mounted on a beam member. There are individual compliant interfaces built into the fin members such that a good thermal contact can be ensured with the heat generating semiconductor devices. The modular heat dissipating devices can be stacked up to gain higher cooling capacity or spread around to cover multiple chips on a printed-wiring board.